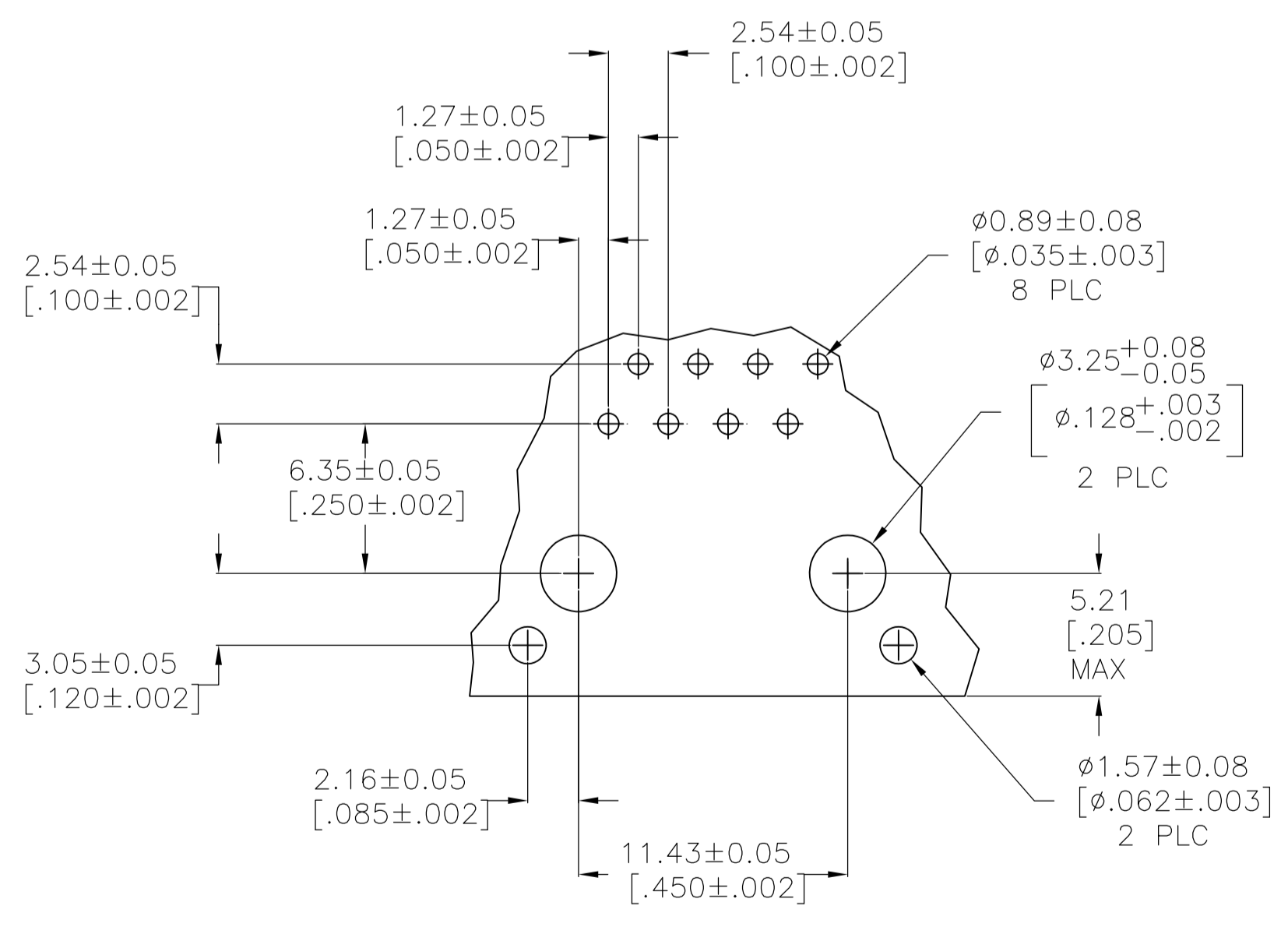
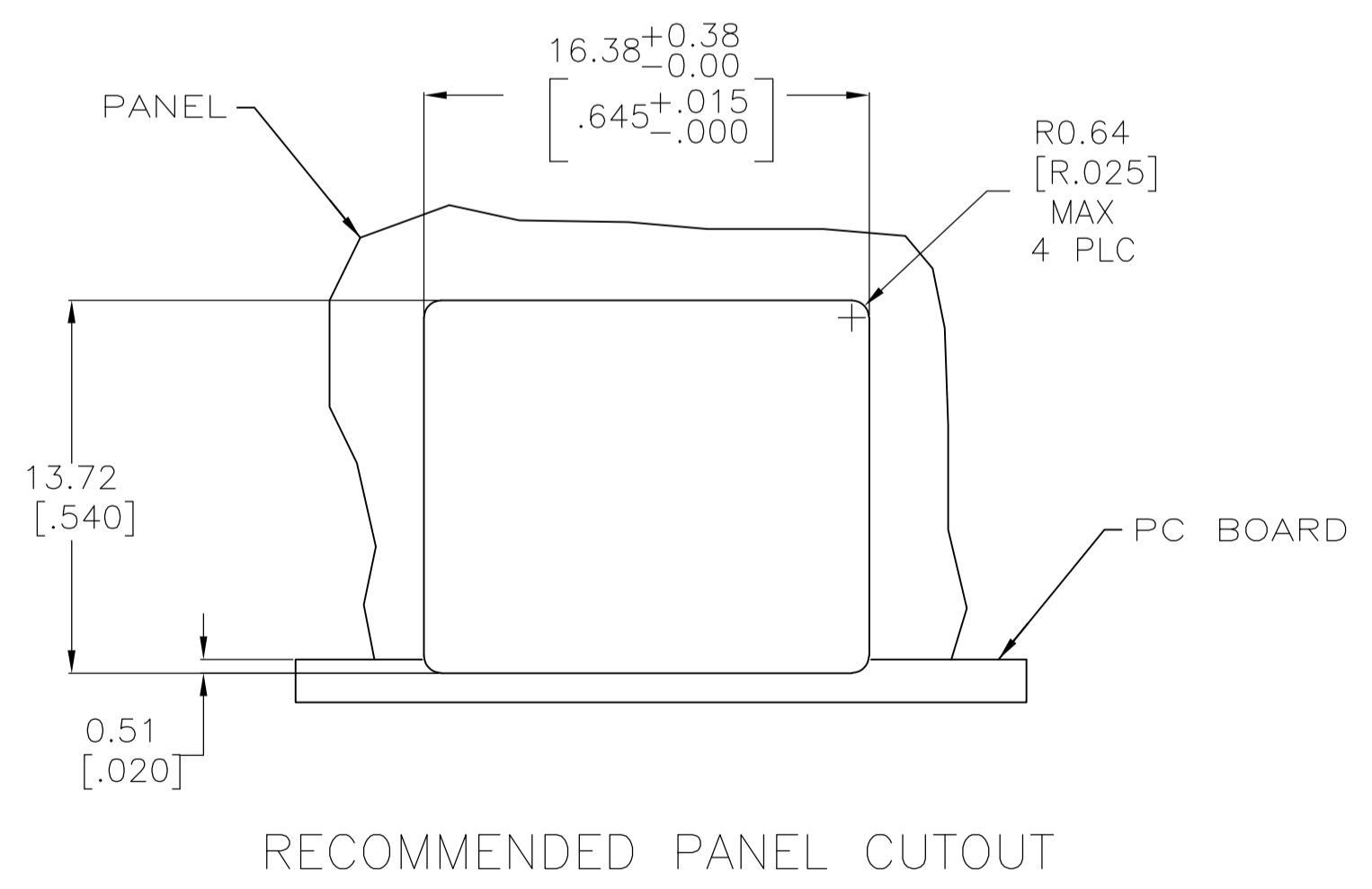


1. MATERIAL:
 HOUSING (SEE TABLE) - COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] THICK NICKEL UNDERPLATE
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0μm [.000120] MINIMUM THICK REFLOWED TIN
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN G GARRETT/L.A. MAYER 04APR2005	CIK J.WESTMAN 04APR2005	APVD S.FLICKINGER 04APR2005	NAME
0 PLC ± -	1 PLC ± -	2 PLC ± 0.13[.005]	3 PLC ± -	4 PLC ± -	ANGLES ± -
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT	RESTRICTED TO
CUSTOMER DRAWING		SCALE 4:1	SHEET 1 OF 1	REV B1	

STE TE Connectivity

MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS

108-1163

114-2048

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